TEC0330 TRM

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Overview

The Trenz Electronic TEC0330 FPGA board is a PCI Express form factor card (PCIe 2.0 or higher) integrating the Xilinx Virtex-7 XC7VX330T FPGA chip. This high-end FPGA card is designed for maximum system performance and intended for use in applications with high demands on system throughput. There is a SO-DIMM socket on the board for standard DDR3 SDRAM extension memory module.

The TEC0330 features HPC (High Pin Count) ANSI/VITA 57.1 compatible FMC interface connector for standard I/O Mezzanine modules. Other interface connectors found on-board include JTAG for accessing FPGA and on-board System Controller CPLD, and also connector with 5 high-speed I/O differential signaling pairs.

The TEC0330 FPGA board is intended to be used as add-on card in a PCle 2.0 or higher capable host systems, it can not be used as a stand-alone device.

Key Features

- Xilinx Virtex-7 FPGA module XC7VX330T-2FFG1157C (commercial temperature range)
- PCI Express 2.0 x8 card with maximum throughput of 4 GB/s
- FMC High Pin Count (HPC) connector
- 8 FPGA MGT lanes available on PCIe interface
- DDR3 SO-DIMM SDRAM socket
- 256-Mbit (32-MByte) Quad SPI Flash memory (for configuration and operation) accessible through:
 - ° FPGA
 - o JTAG port (SPI indirect, bus width x4)
- · External clock input via SMA coaxial connector
- 28 GTH transceivers, each with up to 13.1 Gbit/s data transmission rate
- FPGA configuration through:

 - JTAG connectorQuad SPI Flash memory
- Programmable quad clock generator
- TI LMK04828B ultra low-noise JESD204B compliant clock jitter cleaner
- On-board high-efficiency DC-DC converters
 Up to 202 FPGA I/O pins available on FMC connector (up to 101 LVDS pairs possible)
- System management and power sequencing
- AES bit-stream encryption
- eFUSE bit-stream encryption

Additional assembly options are available for cost or performance optimization upon request.

Block Diagram

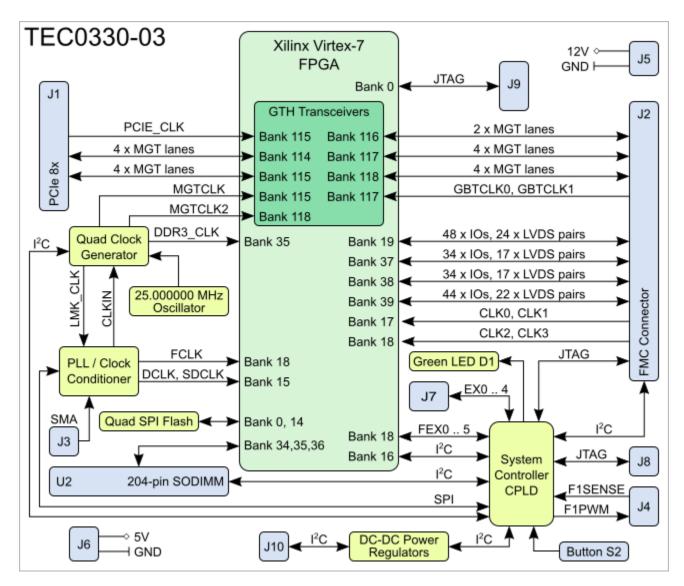


Figure 1: TEC0330-03 block diagram.

Main Components



Figure 2: FPGA board TEC0330-03.

- 1. PCI Express 2.0 x8 connector, J1
- 2. FPGA JTAG connector, J9
- 3. User button, S2
- 4. SO-DIMM socket, U2
- 5. Xilinx Virtex-7 XC7VX330T-2FFG1157C FPGA, U1
- 6. ANSI/VITA 57.1 compliant FMC HPC connector, J2
- 7. SMA coaxial connector for external clock input, J3
- 8. System Controller CPLD JTAG connector, J8
- 9. I²C connector for LT LTM4676 step-down DC-DC regulator, J10
- 10. IDC header for access to 5 x high-speed data lanes (LVDS pairs), J7
- 11. 4-wire PWM fan connector, J4
- **12.** 6-pin 12V power connector, J5
- 13. Reference clock generator @10.0 MHz (P5146) , U11
- 14. LDO DC-DC regulator @3.3V (LMK_3V3) (TI TPS74901RGWR), U21
- 15. 256 Mbit Quad SPI Flash Memory (Micron N25Q256A), U12
- 16. Cooling fan 5VDC M1 (45X5MM, 0.7W, 1.06CFM)
- 17. System Controller CPLD (Lattice Semiconductor LCMXO2-1200HC), U5
- 18. Ultra low jitter clock synthesizer (TI LMK04828B), U9
- 19. Step-down DC-DC regulator @1.0V (LT LTM4676), U4
- 20. Step-down DC-DC regulator @1.5V (VCC1V5) (LT LTM4676, U3
- **21.** I²C Programmable quad clock generator (Silicon Labs Si5338A), U13
- 22. 4A PowerSoC DC-DC converter @1.8V (Altera EN6347QI, U20
- 23. LDO DC-DC regulator @1.0V (MGTAVCC_FPGA) (TI TPS74401RGW), U18
- 24. LDO DC-DC regulator @1.2V (MGTAVTT_FPGA) (TI TPS74401RGW), U17
- 25. 4A PowerSoC DC-DC converter @3.3V (3V3FMC) (Altera EN6347QI), U15
- 26. 4A PowerSoC DC-DC converter @1.8V (FMC_VADJ) (Altera EN6347QI), U7

Initial Delivery State

Storage device name	Content	Notes
SPI Flash OTP Area	Empty, not programmed	Except serial number programmed by flash vendor.
SPI Flash Quad Enable bit	Programmed	-
SPI Flash main array	Demo design	-
eFUSE USER	Not programmed	-
eFUSE Security	Not programmed	-

Signals, Interfaces and Pins

FMC Connector

The high-pin count (HPC) FMC (FPGA Mezzanine Card) connector (J2) is a standard ANSI/VITA 57.1 modular interface to the FPGA and provides access to numerous FPGA I/O pins for use by other mezzanine modules and expansion cards. The FMC connector supports single ended I/O (with several VCCIO voltages available) and LVDS I/O signaling.

The I/O signals are routed from the FPGA I/O banks to the FMC connector as LVDS pairs:

FPGA Bank	I/O Signals	LVDS pairs	Bank Voltage (VCCO)	Notes
Bank 19	92	46	1.8V	-
Bank 39	42	21	VIO_B_FMC	Bank voltage VIO_B_FMC must be supplied by FMC connector pins J2-J39, J2-K40. Bank's VREF_B_M2C signal is routed to the FMC connector pin J2-K1 (external reference voltage).
Bank 37	34	17	1.8V	Bank's VREF_A_M2C signal is routed to the FMC connector pin J2-H1 (external reference voltage).
Bank 38	34	17	1.8V	Bank's VREF_A_M2C signal is routed to the FMC connector pin J2-H1 (external reference voltage).

Table 2: Overview of the FPGA I/O bank signals routed to the FMC.

There are also 10 high-speed MGT lanes (Xilinx GTH transceivers) from different FPGA MGT banks routed to the FMC connector. Following MGT lanes are available on the FMC connector:

FPGA Bank	I/O Signals	LVDS Pairs	MGT Lanes	MGT Bank's Reference Clock
116	8	4	2	1 clock-signal from clock synthesizer U9 to bank's pins T6/T5.
117	16	8	4	2 clock-signals from clock FMC connector GBTCLK0_M2C and GBTCLK1_M2C (pins J2-D4/J2-D5 and J2-B20/J2-B21) to bank's pins M6/M5 and P6/P5.
118	16	8	4	1 reference clock from clock synthesizer U9 to bank's pins F6/F5
				1 reference clock from programmable quad clock generator U13 to bank's pins H6/H5.

Table 3: Overview of MGT banks lanes routed to the FMC connector.

The FMC connector has also two reference clock input pairs (LVDS) routed to the FPGA MGT bank 117, see also section MGT lanes.

There are also JTAG, I²C interface and power good control signals routed between FMC connector and System Controller CPLD:

Interface	I/O Signals	Schematic Name / FMC Pin	Connected to	Notes
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JTAG	5	FMC_TRST, pin D34	SC CPLD, bank 2	VCCIO: 3V3PCI.
		FMC_TCK, pin D29		
		FMC_TMS, pin D33		
		FMC_TDI, pin D30		
		FMC_TDO, pin D31		
I ² C	2	FMC_SCL, pin C30	SC CPLD, bank 2	VCCIO: 3V3PCI.
		FMC_SDA, pin C31		I ² C-lines 3V3PCI pulled-up.
Control lines	3	FMC_PRSNT_M2C_L, pin H2	SC CPLD, bank 1	PG - Power Good signal.
		FMC_PG_C2M, pin D1 (3V3FMC pull-up)		C2M - carrier to mezzanine module.
		FMC_PG_M2C, pin F1 (3V3FMC pull-up)		M2C - mezzanine module to carrier.
				Internal System Controller CPLD signal assignment:
				FEX_0_N <= FMC_PG_M2C
				FMC_PG_C2M <= FMC_PRSNT_M2C_L

Table 4: FMC connector pin-outs of available interfaces to the System Controller CPLD.

FPGA bank 17 and 18 clock inputs from FMC connector:

Schematic Name	FMC Connector Pins	FPGA Bank	FPGA Pins
CLK0_P, CLK0_N	H4, H5	17	R28, R29
CLK1_P, CLK1_N	G2, G3	17	P29, P30
CLK2_P, CLK2_N	K4, K5	18	G31, G31
CLK3_P, CLK3_N	J2, J3	18	H29, H30

Table 5: FMC connector pin-outs for reference clock input.

Several VCCIO voltages are available on the FMC connector for FPGA I/O banks:

Schematic Name	Max Current	FMC Connector Pins	Notes
12V	1A	C35, C37	Externally supplied 12V
3V3PCI	20mA	D32	Supplied by the PCIe interface
3V3FMC	3A	D36, D38, D40, C39	Supplied by DC-DC converter U15
VIO_B_FMC	External supply	J39, K40	Externally supplied VCCO to HB FPGA bank 39
FMC_VADJ	4A	H40, G39, F40, E39	Fixed to 1.8V, supplied by DC-DC converter U7

Table 6: Available VCCIO voltages on FMC connector.

PCI Express Interface

The TEC0330 FPGA board is a PCI Express card designed to fit into systems with PCI Express x8 slots (PCIe 2.0 or higher) and is PCIe Gen. 2 capable. See next section for the overview of FPGA MGT lanes routed to the PCIe interface.

MGT Lanes

MGT (Multi Gigabit Transceiver) lane consists of one receive and one transmit (RX/TX) differential pairs, four signals total per one MGT lane. Following table lists lane number, MGT bank number, transceiver type, signal schematic name, FMC connector pin connection and FPGA pin connection information.

FPGA to FMC Connector MGT lanes

Lane	FPGA Bank	Туре	Signal Name	FPGA Pin	FMC Pin
0	117	GTH	• DP0_M2C_P • DP0_M2C_N • DP0_C2M_P • DP0_C2M_N	 MGTHRXP0_117, N4 MGTHRXN0_117, N3 MGTHTXP0_117, M2 MGTHTXN0_117, M1 	J2A-C6J2A-C7J2A-C2J2A-C3
1	117	GTH	• DP1_M2C_P • DP1_M2C_N • DP1_C2M_P • DP1_C2M_N	 MGTHRXP1_117, L4 MGTHRXN1_117, L3 MGTHTXP1_117, K2 MGTHTXN1_117, K1 	J2A-A2J2A-A3J2A-A22J2A-A23
2	117	GTH	 DP2_M2C_P DP2_M2C_N DP2_C2M_P DP2_C2M_N 	 MGTHRXP2_117, K6 MGTHRXN2_117, K5 MGTHTXP2_117, H2 MGTHTXN2_117, H1 	J2A-A6J2A-A7J2A-A26J2A-A27
3	117	GTH	DP3_M2C_PDP3_M2C_NDP3_C2M_PDP3_C2M_N	 MGTHRXP3_117, J4 MGTHRXN3_117, J3 MGTHTXP3_117, F2 MGTHTXN3_117, F1 	J2A-A10J2A-A11J2A-A30J2A-A31
4	118	GTH	• DP4_M2C_P • DP4_M2C_N • DP4_C2M_P • DP4_C2M_N	 MGTHRXP0_118, G4 MGTHRXN0_118, G3 MGTHTXP0_118, D2 MGTHTXN0_118, D1 	J2A-A14J2A-A15J2A-A34J2A-A35

Table 8: FPGA to FMC connector MGT lanes overview (continue on next page).

FPGA to FMC Connector MGT lanes (continued)

Lane	FPGA Bank	Туре	Signal Name	FPGA Pin	FMC Pin
5	118	GTH	 DP5_M2C_P DP5_M2C_N DP5_C2M_P DP5_C2M_N 	 MGTHRXP1_118, E4 MGTHRXN1_118, E3 MGTHTXP1_118, C4 MGTHTXN1_118, C3 	J2A-A18J2A-A19J2A-A38J2A-A39
6	118	GTH	DP6_M2C_PDP6_M2C_NDP6_C2M_PDP6_C2M_N	 MGTHRXP2_118, D6 MGTHRXN2_118, D5 MGTHTXP2_118, B2 MGTHTXN2_118, B1 	J2A-B16J2A-B17J2A-B36J2A-B37
7	118	GTH	• DP7_M2C_P • DP7_M2C_N • DP7_C2M_P • DP7_C2M_N	 MGTHRXP3_118, B6 MGTHRXN3_118, B5 MGTHTXP3_118, A4 MGTHTXN3_118, A3 	J2A-B12J2A-B13J2A-B32J2A-B33

8	116	GTH	DP8_M2C_PDP8_M2C_NDP8_C2M_PDP8_C2M_N	 MGTHRXP2_116, U4 MGTHRXN2_116, U3 MGTHTXP2_116, T2 MGTHTXN2_116, T1 	J2A-B8J2A-B9J2A-B28J2A-B29
9	116	GTH	DP9_M2C_PDP9_M2C_NDP9_C2M_PDP9_C2M_N	 MGTHRXP3_116, R4 MGTHRXN3_116, R3 MGTHTXP3_116, P2 MGTHTXN3_116, P1 	J2A-B4J2A-B5J2A-B24J2A-B25

 Table 8: FPGA to FMC connector MGT lanes overview.

FPGA to PCIe Connector MGT lanes

Lane	FPGA Bank	Туре	Signal Name	FPGA Pin	PCle Pin
0	115	GTH	• PER0_P • PER0_N • PET0_P • PET0_N	 MGTHRXP3_115, AB2 MGTHRXN3_115, AB1 MGTHTXP3_115, AC4 MGTHTXN3_115, AC3 	J1-A16J1-A17J1-B14J1-B15
1	115	GTH	• PER1_P • PER1_N • PET1_P • PET1_N	 MGTHRXP2_115, AD2 MGTHRXN2_115, AD1 MGTHTXP2_115, AE4 MGTHTXN2_115, AE3 	J1-A21J1-A22J1-B19J1-B20
2	115	GTH	• PER2_P • PER2_N • PET2_P • PET2_N	 MGTHRXP1_115, AF2 MGTHRXN1_115, AF1 MGTHTXP1_115, AF6 MGTHTXN1_115, AF5 	J1-A25J1-A26J1-B23J1-B24
3	115	GTH	• PER3_P • PER3_N • PET3_P • PET3_N	 MGTHRXP0_115, AH2 MGTHRXN0_115, AH1 MGTHTXP0_115, AG4 MGTHTXN0_115, AG3 	J1-A29J1-A30J1-B27J1-B28
4	114	GTH	• PER4_P • PER4_N • PET4_P • PET4_N	 MGTHRXP3_114, AK2 MGTHRXN3_114, AK1 MGTHTXP3_114, AJ4 MGTHTXN3_114, AJ3 	J1-A35J1-A36J1-B33J1-B34
5	114	GTH	PER5_PPER5_NPET5_PPET5_N	 MGTHRXP2_114, AM2 MGTHRXN2_114, AM1 MGTHTXP2_114, AL4 MGTHTXN2_114, AL3 	J1-A39J1-A40J1-B37J1-B38
6	114	GTH	• PER6_P • PER6_N • PET6_P • PET6_N	 MGTHRXP1_114, AN4 MGTHRXN1_114, AN3 MGTHTXP1_114, AM6 MGTHTXN1_114, AM5 	J1-A43J1-A44J1-B41J1-B42

7	114	GTH	PER7_PPER7_NPET7_PPET7_N	 MGTHRXP0_114, AP2 MGTHRXN0_114, AP1 MGTHTXP0_114, AP6 MGTHTXN0_114, AP5 	J1-A47J1-A48J1-B45J1-B46
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Table 9: FPGA to PCIe connector MGT lanes overview.

Following table lists reference clock sources of the MGT banks.

Clock Signal	MGT Bank	Source	FPGA Pin	Notes
MGTCLK_5338_P	115	U13, CLK1A	MGTREFCLK0P_115, AB6	On-board Si5338A.
MGTCLK_5338_N	115	U13, CLK1B	MGTREFCLK0N_115, AB5	On-board Si5338A.
PCIE_CLK_P	115	J1-A13, REFCLK+	MGTREFCLK1P_115, AD6	External clock from PCIe slot.
PCIE_CLK_N	115	J1-A14, REFCLK-	MGTREFCLK1N_115, AD6	External clock from PCIe slot.
CLK_SYNTH_DCLKOUT4_P	116	U9, DCLKout4	MGTREFCLK0P_116, T6	On-board LMK04828B.
CLK_SYNTH_DCLKOUT4_N	116	U9, DCLKout4*	MGTREFCLK0N_116, T6	On-board LMK04828B.
GBTCLK0_M2C_P	117	J2-D4	MGTREFCLK0P_117, M6	External clock from FMC connector.
GBTCLK0_M2C_N	117	J2-D5	MGTREFCLK0N_117, M5	External clock from FMC connector.
GBTCLK1_M2C_P	117	J2-B20	MGTREFCLK1P_117, P6	External clock from FMC connector.
GBTCLK1_M2C_N	117	J2-B21	MGTREFCLK1N_117, P5	External clock from FMC connector.
CLK_SYNTH_SDCLKOUT7_P	118	U9, DCLKout7	MGTREFCLK0P_118,F6	On-board LMK04828B.
CLK_SYNTH_SDCLKOUT7_N	118	U9, DCLKout7*	MGTREFCLK0N_118,F5	On-board LMK04828B.
MGTCLK2_5338_P	118	U13, CLK3A	MGTREFCLK1P_118, H6	On-board Si5338A.
MGTCLK2_5338_N	118	U13, CLK3B	MGTREFCLK1N_118, H5	On-board Si5338A.

Table 10: MGT banks reference clock sources.

JTAG Interfaces

There are three JTAG interfaces available on the TEC0330 board:

JTAG Interface	Signal Schematic Name	JTAG Connector Pin	Connected to
CPLD JTAG	CPLD_JTAG_TMS	J8-1	SC CPLD, bank 0, pin 90
VCCIO: 3V3PCI	CPLD_JTAG_TDI	J8-2	SC CPLD, bank 0, pin 94
Connector: J8	CPLD_JTAG_TDO	J8-3	SC CPLD, bank 0, pin 95
	CPLD_JTAG_TCK	J8-4	SC CPLD, bank 0, pin 91
FPGA JTAG	FPGA_JTAG_TMS	J9-4	FPGA, bank 0, pin N9
VCCIO: 1V8	FPGA_JTAG_TMS	J9-6	FPGA, bank 0, pin M8
Connector: J9	FPGA_JTAG_TCK	J9-8	FPGA, bank 0, pin N8
	FPGA_JTAG_TDI	J9-10	FPGA, bank 0, pin L8
FMC JTAG	FMC_TRST	J2-D34	SC CPLD, bank 2, pin 36

VCCIO: 3.3VPCI	FMC_TRST	J2-D29	SC CPLD, bank 2, pin 27
Connector: J2	FMC_TCK	J2-D33	SC CPLD, bank 2, pin 28
	FMC_TMS	J2-D30	SC CPLD, bank 2, pin 31
	FMC_TDO	J2-D31	SC CPLD, bank 2, pin 32

Table 11: JTAG interfaces on TEC0330 board.

On-board Peripherals

System Controller CPLD

The System Controller CPLD is the central system management unit that provides numerous interfaces between the on-board peripherals and to the FPGA module. The signals routed to the CPLD will be linked by the logic implemented in the CPLD firmware, which generates output signals to control the system, the on-board peripherals and the interfaces. So some interfaces between the on-board peripherals and to the FPGA module are by-passed, forwarded and controlled by the System Controller CPLD.

Other tasks of the System Controller CPLD are the monitoring of the power-on sequence, the proper programing of the FPGA module and to display its programming state.

SC CPLD Bank	CPLD Bank's VCCIO
0	3V3PCI
1	3V3PCI
2	3V3PCI
3	1V8

Table 12: VCCIO voltages of CPLD banks.

Following table describes the interfaces and functionalities of the System Controller CPLD not described elsewhere in this TRM:

CPLD Functionality	Interface	Designated CPLD Pins	Connected to	Notes
I ² C interface between on-board peripherals and FPGA	I ² C	• FPGA_IIC_S DA, pin 24 • FPGA_IIC_S CL, pin 25 • FPGA_IIC_O E, pin 19	• FPGA bank 16, pin V29 • FPGA bank 16, pin W29 • FPGA bank 16, pin W26	VCCIO: 1V8, all with pull-up to 1V8. Following devices and connectors are linked to the FPGA_IIC I ² C interface: • DC-DC converter U3 and U4 (LT LTM4676) • Programmable quad clock generator U13 • FMC connector J2 • PCIe connector J1 Note: FPGA_IIC_OE must kept high for I ² C operation. For I ² C slave device addresses refer to the component datasheets.
User I/Os External LVDS pairs	10 I/Os 5 x LVDS pairs	• EX0_P EX4_P • EX0_N EX4_N	• IDC header J7	Can also be used for single-ended signaling.

User I/Os Internal LVDS pairs	13 I/Os 6 x LVDS pairs	• FEX0_P FEX5_P • FEX0_N FEX5_N • FEX_DIR (single-ended I/O)	• FPGA bank 18	VCCIO: 1V8 Can also be used for single-ended signaling. FPGA bank 18 has also reference clock input from FMC connector (CLK2, CLK3) and clock synthesizer U9 (FCLK). Internal signal assignment: FEX_DIR <= FMC_PRSNT_M2C_L
FPGA programming control and state	2 I/Os	• DONE, pin 7 • PROGRAM_ B, pin 8	FPGA bank0, pin V8FPGA bank0, pin U8	VCCIO: 1V8
I ² C interface to programmable quad clock generator	I ² C	• PLL_SCL, pin 14 • PLL_SDA, pin 15	• U13, pin 12 • U13, pin 19	VCCIO: 1V8 Only PLL_SDA has 1V8 pull-up.
Fan PWM control J4	2 I/Os	• F1SENSE, pin 99 • F1PWM, pin 98	J4-3 (active low)J4-4	Internal signal assignment: • FEX_5_P <= F1SENSE • FEX_5_N => F1PWM
Button S2	1 I/O	BUTTON, pin 77	• Switch S2	Functionality depends on CPLD firmware, activating pin PROGRAM_B (active low) and LED1 in standard configuration.
LED1	1 I/O	• LED1, pin 76	• LED D1 (green)	Fast blinking, when FPGA is not programmed. Internal signal assignment: LED1 <= Button S2 or FEX0_P
PCIe control line RESET_B	1 I/O	PCIE_RSTB, pin 37	• J1-A11	Internal signal assignment: • FEX_4_N <= PCIE_RSTB
Control interface to clock synthesizer U9 (TI LMK04828B)	SPI (3 I /Os), 4 I/Os	CLK_SYNTH _SDIO, pin 75 CLK_SYNTH _SCK, pin 74 CLK_SYNTH _RESET, pin 54 CLK_SYNTH _CS, pin 53 CLK_SYNTH _SYNC, pin 52 LMK_STATO, pin 62 LMK_STAT1, pin 63	 U9, pin 20 U9, pin 19 U9, pin 5 U9, pin 18 U9, pin 6 U9, pin 31 U9, pin 48 	Pull up to 3V3PCI. Internal signal assignment: LMK_SCK <= FEX_1_P LMK_SDIO <= FEX_1_N LMK_CS <= FEX_3_P LMK_SYNC <= EX_3_N LMK_RESET <= FEX_4_P FEX_2_P => LMK_SDIO (FEX_2_N must be 0) LMK_STAT0 and LMK_STAT1 signals are not used.

Control Interface to DC-DC converters U3 and U4 (both LTM4676)	I ² C (2 I/Os), 2 I/Os	LTM_SCL, pin 67 LTM_SDA, pin 66 LTM1_ALERT, pin 65 LTM2_ALERT, pin 64	 U4, pin E6 and U3, pin E6 U4, pin D6 and U3, pin D6 U4, pin E5 U3, pin E5 	3V3 pull-ups. LTM I ² C interface is also accessible trough header J10. LTM1_ALERT and LTM2_ALERT signals are not used.
Power-on sequence and monitoring	6 I/Os	 EN_1V8, pin 58 PG_1V8, pin 59 EN_FMC_VA DJ, pin 60 PG_FMC_VA DJ, pin 61 EN_3V3, pin 51 PG_3V3, pin 57 	 U20, pin 27 U20, pin 28 U7, pin 27 U7, pin 28 U15, pin 27 U15, pin 27 	Sequence of the supply voltages depend on the System Controller CPLD firmware. EN_1V8, EN_3V3 and EN_FMC_VADJ will be set simultaneously at start-up. PG signals will not be evaluated.

Table 13: Overview of the System Controller CPLD functions.

SO-DIMM Socket for DDR3 SDRAM

The TEC0330 board supports additional DDR3 SO-DIMM via 204-pin socket U2. The DDR3 memory interface is routed to the FPGA banks 34, 35 and 36.

The reference clock signal for the DDR3 interface is generated by the quad programmable clock generator U13 and is applied to the FPGA bank 35.

There is also a I²C interface between the System Controller CPLD and the DDR3 SDRAM memory:

Interface Signals Schematic Name	System Controller CPLD Pin	DDR3 Memory Interface Pin
DDR3_SDA	Bank 2, pin 48	Pin 200 (3V3PCI pull-up)
DDR3_SCL	Bank 2, pin 49	Pin 202 (3V3PCI pull-up)

Table 14: I²C-interface between SC CPLD and DDR3 SDRAM memory.

Quad SPI Flash Memory

An 256 Mbit (32 MByte) Quad SPI Flash Memory (Micron N25Q256A, U12) is provided for FPGA configuration file storage. After configuration process completes the remaining free memory can be used for application data storage. All four SPI data lines are connected to the FPGA allowing x1, x2 or x4 data bus widths to be used. The maximum data transfer rate depends on the bus width and clock frequency. The memory can be accessed indirectly by the FPGA JTAG port (J9) by implementing the functional logic for this purpose inside the FPGA.

Clock sources

The TEC0330 FPGA board has a sophisticated clock generation and conditioning system to meet the requirements of the Xilinx Virtex-7 GTH units with data transmission rates up to 13.1 Gb/s.

List of on-board and external reference clock signals of the TE0330 board:

Clock Source	Schematic Name	Frequency	Clock Destination
SMA coaxial connector, J3	CLK_SYNTH_CLKIN0_P,	User	Clock synthesizer U9, pins 37/38
	CLK_SYNTH_CLKIN0_N (GND)		

RAKON P5146LF oscillator, U11	-	10.0 MHz	Clock synthesizer U9, pins 43/44
SiTime SiT8208 oscillator, U14	CLK_25MHz	25.0 MHz	Programmable quad clock generator U13, pin 3
FMC connector J2, pins H4/H5	CLK0_P, CLK0_N	User	FPGA bank 17, pins R28/R29
FMC connector J2, pins G2/G3	CLK1_P, CLK1_N	User	FPGA bank 17, pins P29/P30
FMC connector J2, pins K4/K5	CLK2_P, CLK2_N	User	FPGA bank 18, pins G30/G31
FMC connector J2, pins J2/J3	CLK3_P, CLK3_N	User	FPGA bank 18, pins H29/H30
FMC connector J2, pins D4/D5	GBTCLK0_M2C_P,	User	FPGA bank 117, pins M6/M5
	GBTCLK0_M2C_N		
FMC connector J2, pins B20/B21	GBTCLK1_M2C_P,	User	FPGA bank 117, pins P6/P5
	GBTCLK1_M2C_N		
PCIe interface J1, pins A13/A14	PCIE_CLK_P,	100 MHz	FPGA bank 115, pins AD6/AD5
	PCIE_CLK_N	(PCIe spec.)	

Table 15: Clock generator sources overview.

Programmable Clock Generator

There is a Silicon Labs I²C programmable quad clock generator Si5338A (U13) on-board. It's output frequencies are programmable via FPGA I²C interface using slave device address 0x70 (corresponding I²C logic has to be implemented in FPGA design).

A 25 MHz (U14) oscillator is connected to pin 3 (IN3) and is used to generate the output clocks.

Si5338A (U13) Input	Signal Schematic Name	Notes
IN1/IN2	CLKIN_5338_C_P, CLKIN_5338_C_N	Reference clock signal from clock synthesizer U9 (100 nF decoupling capacitors and 100 termination resistor).
IN3	Reference clock oscillator input, SiTime SiT8208AI (U14).	25.0 MHz fixed frequency.
IN4/IN6	Connected to the GND.	LSB (pin 'IN4') of the default I ² C-adress 0x70 is zero.
IN5	Not connected	-
Si5338A (U13) Output	Signal Schematic Name	Notes
CLK0 A/B	DDR3_CLK_P, DDR3_CLK_N	DDR3-RAM reference clock signal to FPGA bank 35.
CLK1 A/B	MGTCLK_5338_C_P, MGTCLK_5338_C_N	Reference clock signal to FPGA bank 115 MGT (100 nF decoupling capacitors and 100 termination resistor).
CLK2 A/B	LMK_CLK_P, LMK_CLK_N	Input clock signal to clock synthesizer U9 (100 nF decoupling capacitors).
CLK3 A/B	MGTCLK2_5338_C_P, MGTCLK2_5338_C_N	Reference clock signal to FPGA bank 118 MGT (100 nF decoupling capacitors and 100 termination resistor).

Table 16: I/O pin description of programmable clock generator Si5338A.

Ultra low-noise high-performance clock synthesizer

The TEC0330 board utilizes an ultra low jitter clock synthesizer TI LMK04828B (U9) for conditioning and generating clean clock signals which are necessary for the GTH units of the Xilinx Virtex-7 FPGA module.

The clock synthesizer can be controlled and programmed by its SPI interface (SPI slave) and other control lines, which are routed to the FPGA module (SPI master) and by-passed trough the System Controller CPLD. See section 'System Controller CPLD' for more detailed information.

Logic needs to be generated inside the FPGA module to utilize SPI bus correctly.

LMK04828B (U9) input	signal schematic name	Note
Status_LD1, Status_LD2	LMK_STAT0, LMK_STAT1	Connected to System Controller CPLD, not implemented in current CPLD firmware.
SPI interface and control lines	see section 'System controller CPLD'	The clock synthesizer IC is accessible to the FPGA via the SPI interface and control lines, which are routed through the System Controller CPLD.
CLKin0, CLKin0*	CLK_SYNTH_CLKIN0_P, CLK_SYNTH_CLKIN0_N	Input reference clock signal via SMA coaxial connector J3, connected to CLKin0* via serial decoupling capacitor 100nF. CLKin0 to connected to GND via serial decoupling capacitor 100nF.
CLKin1, CLKin1*	CLK_SYNTH_CLKIN1_P, CLK_SYNTH_CLKIN1_N	Input reference clock signal from programmable quad clock generator Si5338A (U13) via serial decoupling capacitor 100nF.
OSCin, OSCin*	-	Signal from reference clock oscillator RAKON P51446LF, fixed to 10.0 MHz.
LMK04828B (U9) output	signal schematic name	Note
DCLKout0, DCLKout0*	CLK_SYNTH_DCLKOUT 0_P, CLK_SYNTH_DCLKOUT 0_N	Reference clock signal to FPGA bank 15 pins AD29/AE29.
SDCLKout1, SDCLKout1*	CLK_SYNTH_SDCLKO UT1_P, CLK_SYNTH_SDCLKO UT1_N	Reference clock signal to FPGA bank 15 pins AE31/AF31.
DCLKout2, DCLKout2*	CLKIN_5338_P, CLKIN_5338_N	Reference clock signal to programmable quad clock generator Si5338A (U13) (100 nF decoupling capacitors and 100 termination resistor).
DCLKout4, DCLKout4*	CLK_SYNTH_DCLKOUT 4_P, CLK_SYNTH_DCLKOUT 4_N	Reference clock signal to FPGA MGT bank 115, pins T6/T5.
SDCLKout7, SDCLKout7*	CLK_SYNTH_SDCLKO UT7_P, CLK_SYNTH_SDCLKO UT7_N	Reference clock signal to FPGA MGT bank 118, pins F6/F5.
OSCout0, OSCout0*	CLK_SYNTH_CLKIN2_P, CLK_SYNTH_CLKIN2_N	Reference clock signal to FPGA bank 18, pins J30/J31 (100 nF decoupling capacitors).

Table 17: Pin description of clock synthesizer TI LMK04828B.

Power and Power-On Sequence

Power Supply

6-pin 12V power connector J5 is the main power supply of the TEC0330 FPGA board, minimum current capability of 3A for system startup is recommended

Power Consumption

Power Input	Typical Current
12V (J5)	TBD
3V3PCI (J1)	TBD

Table 18: Typical power consumption.

TBD - To Be Determined.

Power-On Sequence

The on-board voltages of the TEC0330 FPGA board are powered up in predefined sequence after the external voltages 12V on connector J5 and 3V3PCI on connector J1 become available.

Core voltages and main supply voltages have to reach stable state and their "Power Good" signals have to be asserted before other voltages like PL bank's I/O voltages can be powered up.

Following diagram describes the sequence of enabling the on-board voltages:

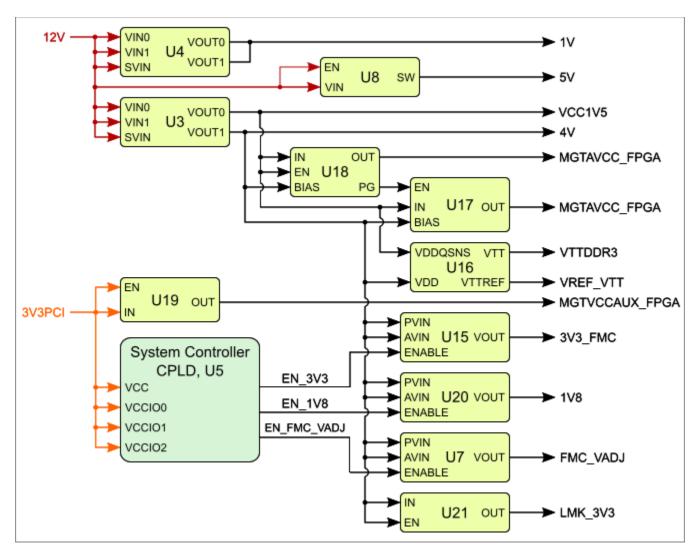


Figure 3: FPGA board TEC0330-03 power-on sequence diagram.

Bank Voltages

Bank	Schematic Name	Voltage	Range	Notes
0	1V8	1.8V	HP: 1.2V to 1.8V	Config bank (fixed to 1.8V) / JTAG interface.
14	1V8	1.8V	HP: 1.2V to 1.8V	QSPI flash memory interface.
15	1V8	1.8V	HP: 1.2V to 1.8V	Reference clock input.
16	1V8	1.8V	HP: 1.2V to 1.8V	I ² C interface of FPGA.
17	1V8	1.8V	HP: 1.2V to 1.8V	Reference clock input.
18	1V8	1.8V	HP: 1.2V to 1.8V	Reference clock input / I/O's to CPLD.
34	VCC1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface.

35	VCC1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface.
36	VCC1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface.
114	MGTAVCC_FPGA	1.0V	MGT bank supply voltage	MGT banks with Xilinx GTH transceiver units.
115	MGTVCCAUX_FPGA	1.8V	MGT bank auxiliary supply voltage	
116	MGTAVTT_FPGA	1.2V	MGT bank termination circuits voltage	
117				
118				
19	1V8	1.8V	HP: 1.2V to 1.8V	I/Os routed to FMC, usable as LVDS pairs.
37	1V8	1.8V	HP: 1.2V to 1.8V	I/Os routed to FMC, usable as LVDS pairs.
38	1V8	1.8V	HP: 1.2V to 1.8V	I/Os routed to FMC, usable as LVDS pairs.
39	VIO_B_FMC	user	HP: 1.2V to 1.8V	I/Os routed to FMC, usable as LVDS pairs.

Table 19: Range of FPGAs bank voltages.

See Xilinx Virtex-7 datasheet (DS183) for the voltage ranges allowed.

Power Rails

Connector / Pin	Voltage	Direction	Notes
J4, pin 2	12V (filtered)	Output	4-wire PWM fan connector supply voltage
J6, pin 2	5V (filtered)	Output	Cooling fan M1 supply voltage
J8, pin 6	3V3PCI	Output	VCCIO CPLD JTAG
J9, pin 2	1V8	Output	VCCIO FPGA JTAG
J2, pin C35 / C37	12V	Output	VCCIO FMC
J2, pin D32	3V3PCI	Output	VCCIO FMC
J2, pin D36 / D38 / D39 / D40	3V3FMC	Output	VCCIO FMC
J2, pin H1	VREF_A_M2C	Input	VREF voltage for bank 37 / 38
J2, pin K1	VREF_B_M2C	Input	VREF voltage for bank 39
J2, pin J39 / J40	VIO_B_FMC	Input	PL I/O voltage bank 39 (VCCO)
J2, pin H40 / G39 / F40 / E39	FMC_VADJ	Output	VCCIO FMC (fixed to 1.8V)
J1, pin A10 / A11 / B8	3V3PCI	Input	PCIe interface supply voltage
J5, pin 1 / 2 / 3	12V	Input	Main power supply connector

 Table 20: Power rails and corresponding connectors of the FPGA board.

Technical Specifications

Absolute Maximum Ratings

Parameter	Min	Max	Units	Notes	Notes
12V power supply voltage	11.4	12.6	V	12V ± 5 %	ANSI/VITA 57.1 FPGA Mezzanine Card (FMC) standard
PL I/O voltage for HP banks	-0.55	VCCO_X + 0.55	V	-	Xilinx datasheet DS183

GTH transceivers	-0.5	1.26	V	-	Xilinx datasheet DS183
Voltage on System Controller CPLD pins	-0.3	3.6	V	-	MachXO2 family datasheet
Storage temperature	-55	+125	°C	-	MachXO2 family datasheet

Table 21: Absolute maximum ratings.

Recommended Operating Conditions

Parameter	Min	Max	Units	Notes	Reference Document	
12V power supply voltage	11.4	12.6	V	12V ± 5 %	ANSI/VITA 57.1 FPGA Mezzanine Card (FMC) standard	
PL I/O voltage for HP banks	-0.2	VCCO_X + 0.2	V	-	Xilinx datasheet DS183	
GTH transceivers	(*)	(*)	-	-	Xilinx datasheet DS183	
Voltage on System Controller CPLD pins	3.135	3.6	V	-	MachXO2 family datasheet	

Table 22: Recommended operation conditions.



Check Xilinx datasheet (DS183) for complete list of absolute maximum and recommended operating ratings.

Operating Temperature Ranges

Commercial grade: 0°C to +70°C.

Industrial grade: -40°C to +85°C.

The FPGA board's operating temperature range depends also on customer design and cooling solution. Please contact us for options.

Physical Dimensions

• board size: 106,65mm × 167,65mm

Mating height with standard FMC connectors: 10 mm

PCB thickness: 1.65 mm

All dimensions are given in millimeters.

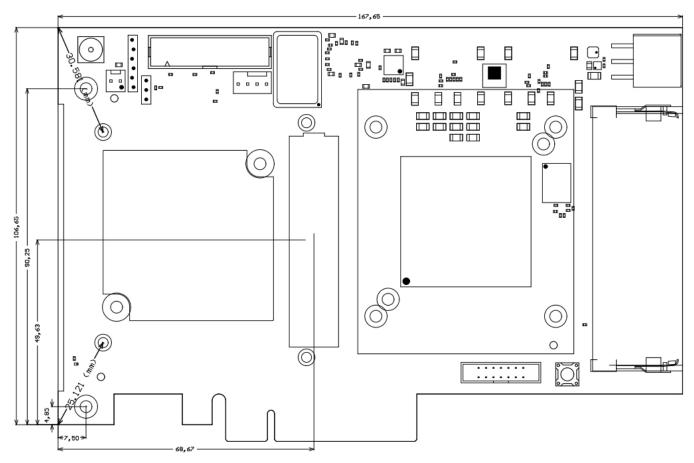


Figure 4: Physical dimensions of the TEC0330-03 board.

Hardware Revision History

Date	Revision	Notes	PCN	Documentation
-	03	First production release	-	-
2015-11-05	02	Prototype	-	-
-	01	Prototype	-	-

Table 23: Hardware revision history.

Hardware revision number is printed on the PCB board together with the model number separated by the dash.



Figure 5: TE0330 board hardware revision number.

Document Change History

Date	Revision	Contributors	Description
Error rendering macro 'page-info' Ambiguous method overloading for method jdk. proxy241.\$Proxy3496#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages. Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core. ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core. core.ContentEntityObject]	Unknown macro: 'metadata'	Jan Kumann	MGT Lanes section added. MGT banks clock sources table added. Fixed signal names in JTAG section. On- board periphera Is section added. Weight section removed.
2017-08-30	v.15	Jan Kumann	Block diagram changed. Physical dimensions image changed. New product images. Corrections in content. Template revision added.
2017-03-15	v.3	Ali Naseri	Initial TRM release.

Table 24: Document change history.

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